Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

Except below description page
 "Request for your special attention and precautions in using the technical information and semiconductors described in this book"

Nuvoton Technology Corporation Japan

Panasonic

MOS FET

FC4B21300L

FC4B21300L

Gate resistor installed Dual N-channel MOS FET

For lithium-ion secondary battery protection circuits

■ Features

- Source-source ON resistance:Rss(on) typ. = 70 m Ω (VGS = 4.5 V)
- CSP(Chip Size Package)
- · RoHS compliant (EU RoHS / MSL:Level 1 compliant)
- Marking Symbol: 29

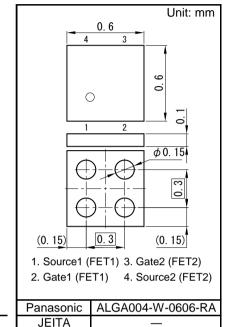
■ Packaging

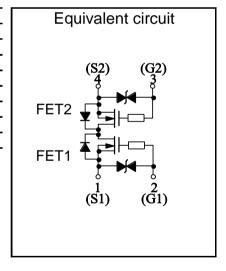
Embossed type (Thermo-compression sealing) : 20 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

| Parameter | Symbol | Rating | Unit |
|---------------------------|--------|-------------|------|
| Source-source Voltage | VSS | 12 | V |
| Gate-source Voltage | VGS | ±8 | V |
| Source Current (DC) | IS *1 | 1.5 | Α |
| | IS *2 | 2 | Α |
| Source Current (Pulsed) | ISp *3 | 15 | Α |
| Total Power Dissipation | PD *1 | 0.32 | W |
| | PD *2 | 0.6 | W |
| Channel Temperature | Tch | 150 | °C |
| Storage Temperature Range | Tstg | -55 to +150 | °C |
| Thermal Resistance (ch-a) | Rth *1 | 390 | °C/W |
| | Rth *2 | 208 | °C/W |

- Note *1 Mounted on FR4 board ($25.4~\text{mm} \times 25.4~\text{mm} \times t1.0~\text{mm}$) using the minimum recommended pad size ($36\mu\text{m}$ Copper).
 - *2 Mounted on Ceramic substrate (70 mm \times 70 mm \times t1.0 mm).
 - *3 $t = 10 \mu s$, Duty Cycle $\leq 1 \%$





Code

Panasonic

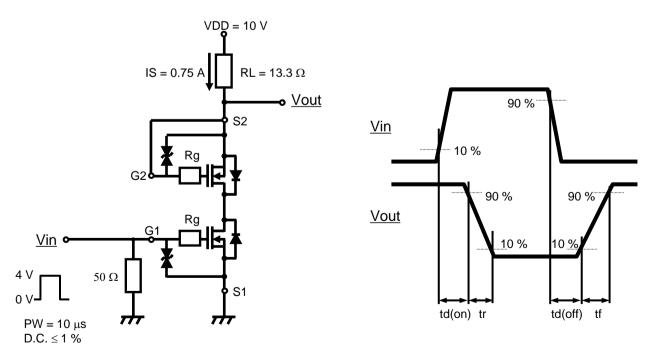
■ Electrical Characteristics Ta = 25 °C ± 3 °C

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit | |
|-----------------------------------|----------|--|------|------|------|------|--|
| Source-source Breakdown Voltage | VSSS | IS = 1 mA, VGS = 0 V | 12 | | | V | |
| Zero Gate Voltage Source Current | ISSS | VSS = 12 V, VGS = 0 V | | | 1.0 | μΑ | |
| Gate-source Leakage Current | IGSS | $VGS = \pm 8 \text{ V}, VSS = 0 \text{ V}$ | | | ±10 | | |
| | | $VGS = \pm 5 V$, $VSS = 0 V$ | | | ±1.0 | μΑ | |
| Gate-source Threshold Voltage | Vth | IS = 0.03 mA, VSS = 10 V | 0.35 | 0.90 | 1.4 | V | |
| Source-source On-state Resistance | RSS(on)1 | IS = 0.75 A, VGS = 4.5 V | 55 | 70 | 95 | mΩ | |
| | RSS(on)2 | IS = 0.75 A, VGS = 3.8 V | 60 | 80 | 110 | | |
| | RSS(on)3 | IS = 0.75 A, VGS = 3.1 V | 65 | 90 | 150 | | |
| | RSS(on)4 | IS = 0.75 A, VGS = 2.5 V | 70 | 115 | 225 | | |
| Body Diode Forward Voltage | VF(s-s) | IF = 0.75 A, VGS = 0 V | | 0.6 | 1.2 | V | |
| Input Capacitance *1 | Ciss | | | 115 | | pF | |
| Output Capacitance *1 | Coss | VSS = 10 V, VGS = 0 V, f = 1 MHz | | 25 | | | |
| Reverse Transfer Capacitance *1 | Crss | | | 18 | | | |
| Turn-on delay Time *1,*2 | td(on) | VDD = 10 V, VGS = 0 to 4.0 V | | 0.10 | | 0 | |
| Rise Time *1,*2 | tr | IS = 0.75 A | | 0.20 | | μS | |
| Turn-off delay Time *1,*2 | td(off) | VDD = 10 V, VGS = 4.0 to 0 V | | 0.27 | | μS | |
| Fall Time *1,*2 | tf | IS = 0.75 A | | 0.22 | | | |
| Total Gate Charge *1 | Qg | VDD = 10 V | | 1.7 | | | |
| Gate-source Charge *1 | Qgs | VGS = 0 to 4.0 V, | | 0.5 | | nC | |
| Gate-drain Charge *1 | Qgd | IS = 0.75 A | | 0.45 | | | |

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

- *1 Guaranteed by design, not subject to production testing
- *2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time

Note2:Measurement circuit



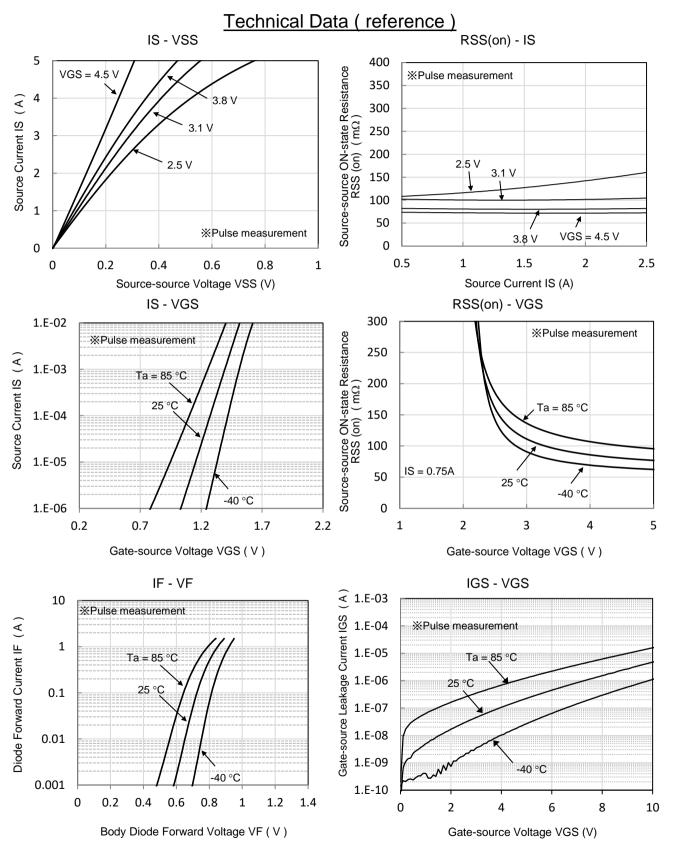
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Established : 2014-12-15 Revised : 2018-12-06

MOS FET

FC4B21300L

Panasonic

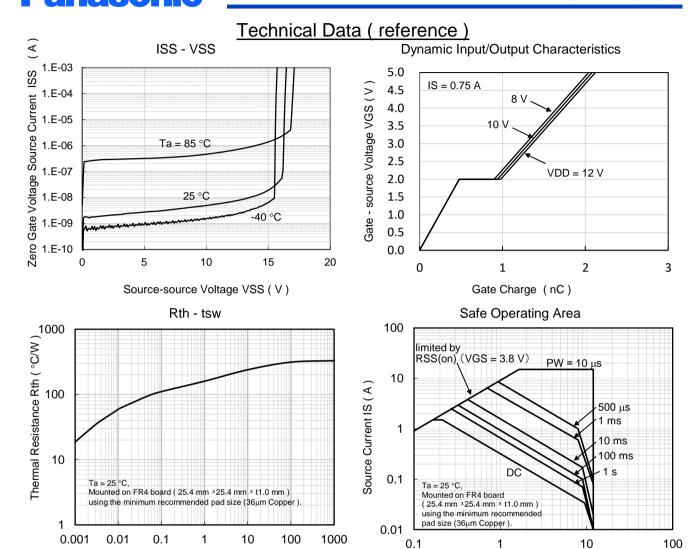


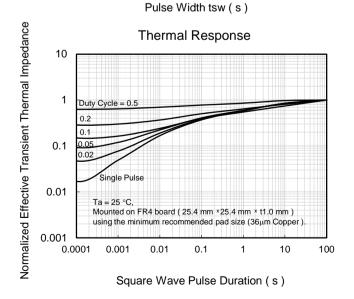
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Established: 2014-12-15 Revised: 2018-12-06 **Panasonic**

MOS FET

FC4B21300L





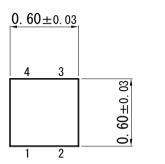
Source-source Voltage VSS (V)

MOS FET

FC4B21300L

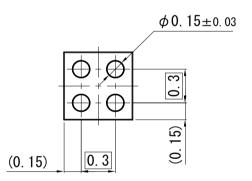
ALGA004-W-0606-RA

Unit: mm

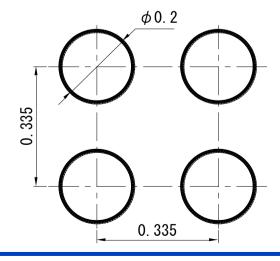








■ Land Pattern (Reference) (Unit: mm)



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